



Amendments to the Claims:

The following claims will replace all prior versions of the claims in this application (in the unlikely event that no claims follow herein, the previously pending claims will remain):

1. (Currently Amended) A substrate with a microstructure formed thereon, the substrate comprising:

a temporary substrate supporting an upper substrate;

a buffer layer formed on an upper surface of the temporary substrate to have a plurality of shapes with air gaps spaced apart from each other at regular intervals; and

an adhesive layer formed between the upper substrate and the buffer layer so that the upper substrate is adhered to the temporary substrate via the adhesive layer and the buffer layer;

wherein the upper substrate is plastic, ~~or~~ metal foil, or a very thin substrate, and has a substantially higher flexibility than that of the temporary substrate, and on which a device is formed ~~at a process of manufacturing the device~~;

wherein the buffer layer is not a component of the device which is formed on the upper substrate; and

wherein the temporary substrate and air gaps are ~~is~~ removed from the upper substrate after the manufacturing process of the device.

2. (Original) The substrate as claimed in claim 1, wherein the temporary substrate is made of at least one of Si, SiO₂, Al₂O₃, copper, copper alloy, aluminum, aluminum alloy, and glass.

3. (Original) The substrate as claimed in claim 1, wherein the buffer layer is made of at least one of SiO₂, Al₂O₃, AlON, SiON, Si₃N₄, AlN, SOG (spin-on-glass), photosensitive material, Cu, Cu alloy, Al, and Al alloy.

4. (Original) The substrate as claimed in claim 1, wherein the buffer layer is patterned and etched to form a plurality of shapes arranged in many rows or to form a plurality of shapes arranged in hexahedron or cylindrical islands, with air gaps being spaced apart from

each other at regular intervals.

5. (Original) The substrate as claimed in claim 1, wherein the adhesive layer is made of any one of a double sided tape, a liquid adhesive, and organic film, to withstand a hot process of more than 100° C.

6. (Original) The substrate as claimed in claim 1, wherein the upper substrate is made of any one of plastic, stainless steel, copper, copper alloy, aluminum, aluminum alloy, silicon, and glass.

Claims 7-12 (cancelled)